

## 64-Bit LED Driver for 300 dpi Printers

## Preliminary

## Overview

LC7958NC is a 64-bit constant current LED driver IC
designed to directly drive LED head array.
The output terminals for LED drive are arranged in 2 -row staggered position of $80-\mu \mathrm{m}$ pitch at one side. It enables drive of LED Array of 300-dpi in one side disposition, 600dpi in both sides disposition

## Features and Functions

- Logic voltage (VDD): +5 V $\pm 10 \%$
- LED drive current (IOH): 5.0 mA (TYP)
- Clock frequency (fc): 10 MHz
- Output current control circuit built in
- Mode switching function by the SEL pin
- Chip size: $1.43 \mathrm{~mm} \times 5.39 \mathrm{~mm}$
- Number of pads: 86
- 64-bit shift register circuit
- 64-bit latch circuit
- Output driver on/off switching function
- Constant current circuit
- 64-bit p-channel open drain LED driver
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## LC7958NC

The characteristics shown below are those of devices encapsulated in the SANYO standard ceramic package

## Specifications

## Absolute Maximum Ratings at $\mathrm{Vss}=0 \mathrm{~V}$

| Parameter | Symbol | Conditions | Ratings | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Power supply voltage | VDD1 | $\mathrm{Ta}=25^{\circ} \mathrm{C}$ | -0.3 to 6.5 | V |
|  | VDD2 |  | -0.3 to 6.5 |  |
| Input voltage | VI | $\mathrm{Ta}=25^{\circ} \mathrm{C}$ | -0.3 to VDD1+ 0.3 | V |
| Output voltage | VO | $\mathrm{Ta}=25^{\circ} \mathrm{C}$ | -0.3 to VDD1 + 0.3 | V |
| Driver output current | IOUT |  | 0 to -10 | mA |
| Operating Junction temperature | Tj |  | -10 to 125 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | Tstg |  | -35 to 125 | ${ }^{\circ} \mathrm{C}$ |

Allowable Operating Ranges at Vss $=0 \mathrm{~V}, \mathrm{VDD} 1=\mathrm{VDD} 2=5 \mathrm{~V} \pm 10 \%, \mathrm{Ta}=0$ to $100^{\circ} \mathrm{C}$

| Parameter | Symbol | Conditions | Ratings |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | min | typ | max |  |
| Power supply voltage | VDD1,VDD2 | VDD1(pad 2), <br> VDD2(pad 6) | 4.5 |  | 5.5 | V |
| Potential difference*1 | VDF | Between VDD1 and VDD2 | -0.3 | 0 | 0.3 |  |
| High-level input voltage | VIH | All inputs | 2.0 |  | VDD1 | V |
| Low-level input voltage | VIL |  | 0 |  | 0.8 | V |
| Clock frequency | fc | CLOCK 1 |  |  | 10 | MHz |
| Clock duty | D CLK | CLOCK 1 | 35 | 50 | 65 | \% |
| Setup time from SI to CLOCK1 | tsc | SI, CLOCK 1 | 30 |  |  | ns |
| Hold time from CLOCK1 to SI | thold | SI, CLOCK 1 | 10 |  |  | ns |
| Setup time from CLOCK1 to LOAD1 | tSL | LOAD 1, CLOCK 1 | 50 |  |  | ns |
| Hold time from LOAD1 to CLOCK1 | tHL | LOAD 1, CLOCK 1 | 50 |  |  | ns |
| LOAD1 pulse width | tWL | LOAD 1 | 40 |  |  | ns |
| CLOCK1 rise/fall time | $\begin{aligned} & \mathrm{tCr} \\ & \mathrm{tCf} \end{aligned}$ | CLOCK 1 |  |  | 35 | ns |
| LOAD1 rise/fall time | $\begin{gathered} \mathrm{tLr} \\ \mathrm{tLf} \end{gathered}$ | LOAD 1 |  |  | 35 | ns |

*1:In case potential difference occurred between VDD1 and VDD2, Driver current value changes. Therefore using it with VDD1=VDD2 is recommended.

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Electrical Characteristics at VSS $=0 \mathrm{~V}, \mathrm{VDD} 1=\mathrm{VDD} 2=5 \mathrm{~V} \pm 10 \%, \mathrm{Ta}=0$ to $100^{\circ} \mathrm{C}$

| Parameter | Symbol | Conditions | Ratings |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | min | typ | max |  |
| High-level output voltage | VOH | LOAD2, S0, CLOCK2: $10=-200 \mu \mathrm{~A}$ | $\begin{array}{\|c} \text { VDD - } \\ 0.5 \end{array}$ |  |  | V |
| Low-level output voltage | VOL | LOAD2, S0, CLOCK2: $10=200 \mu \mathrm{~A}$ |  |  | 0.5 | V |
| Clock frequency | fc |  | 10 |  |  | MHz |
| High-level input current | IIH | All input pads: $\mathrm{VDD1}=5.5 \mathrm{~V}, \mathrm{VI}=$ 5.5 V |  |  | 1.0 | $\mu \mathrm{A}$ |
| Low-level input current | IIL1 | LOAD1, SI, CLOCK1, STROBE,$\begin{aligned} & \mathrm{SEL}, \operatorname{ADJ}(-), \operatorname{ADJ}(+): \mathrm{VDD1} 1=\mathrm{VDD2} \\ & =5.5 \mathrm{~V}, \mathrm{VI}=0 \mathrm{~V} \end{aligned}$ |  |  | -1.0 | $\mu \mathrm{A}$ |
|  | IIL2 |  | -8 | -25 | -50 |  |
|  | IIL3 |  | -40 | -100 | -200 |  |
| High-level output current | IOH1 | DO1 to DO64: operation mode 1, $\begin{aligned} & \mathrm{VDD1}=\mathrm{VDD2}=5.0 \mathrm{~V}, \mathrm{VO}=1.6 \mathrm{~V}, \\ & \mathrm{VREF}=1.8 \mathrm{~V} \end{aligned}$ | -3.7 | -5.0 | -6.7 | mA |
| High-level output current <br> minus correction | IOH2 | DO1 to DO64: operation mode 2 $\begin{aligned} & \mathrm{VDD1}=\mathrm{VDD2}=5.0 \mathrm{~V}, \mathrm{VO}=1.6 \mathrm{~V}, \\ & \mathrm{VREF}=1.8 \mathrm{~V} \end{aligned}$ | -4.5 | -6.0 | -7.0 | \% |
| High-level output current <br> plus correction | IOH3 | DO1 to DO64: operation mode 3 $\begin{aligned} & \mathrm{VDD1}=\mathrm{VDD2}=5.0 \mathrm{~V}, \mathrm{VO}=1.6 \mathrm{~V}, \\ & \mathrm{VREF}=1.8 \mathrm{~V} \end{aligned}$ | +4.5 | +6.0 | +7.0 |  |
| High-level output current relative error between bits | $\Delta \mathrm{IOH}$ | DO1 to DO64: with all bits on | -5.0 |  | +5.0 | \% |
| Output off leakage current | IOL | DO1 to DO64: operation VDD1 = $5.5 \mathrm{~V}, \mathrm{VO}=0 \mathrm{~V}$ |  | 0 | -50 | $\mu \mathrm{A}$ |
| Operating current drain (mode 1) | IDD | VDD1: VDD1 = VDD2 $=5.5 \mathrm{~V}$, VREF $=1.8 \mathrm{~V}$, fc $=10 \mathrm{MHz}$, with DO1 to DO64 off |  | 9.0 | 13.0 | mA |
| Standby current | IDDS | VDD1: VDD1 = VDD2 = 5.5 V, VRE $=1.8 \mathrm{~V}$, with fc stopped, with DO1 to DO64 off |  | 2.5 | 4.0 | mA |

Switching Characteristics at VSS $=0 \mathrm{~V}, \mathrm{VDD} 1=\mathrm{VDD} 2=5 \mathrm{~V} \pm 10 \%, \mathrm{Ta}=0$ to $100^{\circ} \mathrm{C}$


## Equivalent Circuit Block Diagram



## Sample Application Circuit Diagram



Note 1: The electric potential of the IC substrate is at VDD1.
Note 2: The number of cascade connection stages should be within $60 .(10 \mathrm{MHz})$
Note 3: All VDD2 terminals should be bonded.
Note 4: Leave the SEL Terminal of the odd-numbered IC open, and connect the SEL terminal of even-numbered IC with VSS.

Note 5: Apply the stable potential other than the VDD1 and VDD2 lines to the VREF terminal.

## Function Table

1. Shift Register and Latch Blocks

| SEL | CLOCK1 | LOAD1 | Shift register | Latch |
| :---: | :---: | :---: | :---: | :---: |
| High | Falling edge | - | DATA load and DATA shift | - |
|  | Rising edge | - | DATA keep | - |
|  | - | High | - | DATA load |
|  | - | Low | - | DATA keep |
| Low | Falling edge | - | DATA load and DATA shift | - |
|  | Rising edge | - | DATA keep | - |
|  | - | Low | - | DATA load |
|  | - | High | - | DATA keep |

2. Output Block

| $\overline{\text { STROBE }}$ | SI | DO output |
| :---: | :---: | :---: |
| High | " $\times "$ | OFF |
| Low | Low | OFF |
| Low | High | ON |

Note 1: " $\times$ ": don't care

## Establishment of Output Current

| MODE | ADJ(+) | ADJ(-) | Current control <br> resistance | $\mathrm{IOH}($ typ $)$ |
| :---: | :---: | :---: | :---: | :---: |
| 1 | Low | Low | Built in (RINT) | VREF/RINT $\times 10$ |
| 2 | Low | High | Built in (RINT) | VREF/RINT $\times 10 \times 0.94$ |
| 3 | High | Low | Built in (RINT) | VREF/RINT $\times 10 \times 1.06$ |

Note 2: RINT $($ TYP $)=3.61 \mathrm{k} \Omega$
*Complement explanation
Here shows the general usage of the modes 1 to 3 as follows.
MODE 1 is set by connecting the $\mathrm{ADJ}(+)$ and $\mathrm{ADJ}(-)$ terminals with VSS. In the MODE1 state, by cutting the bonding wire connected with $\mathrm{ADJ}(+)$ or $\mathrm{ADJ}(-)$, the IC enters the MODE2 or MODE3, respectively. The current in MODE1 can be corrected by about $-6 \%$ or $+6 \%$ in MODE2 or MODE3, respectively.

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## Ranking by Output Current

1. Test condition: VDD1 $=\mathrm{VDD} 2=5.0 \mathrm{~V}, \mathrm{VREF}=1.8 \mathrm{~V}, \mathrm{VO}=1.6 \mathrm{~V}, \mathrm{Ta}=25^{\circ} \mathrm{C}$
2. Ranking determination: The rank is determined by the average ON current (Iave) of the terminals DO1 to DO64 when the all DO outputs are on.
3. Current width: $(\operatorname{Imax}-\operatorname{Imin}) /(\operatorname{Imax}+\operatorname{Imin}) \approx 2.0 \%$

| Rank |  |  | Specification [mA] |
| :---: | :---: | :---: | :---: |
| A | B | C |  |
| - | 1 | - | -3.700 to -3.853 |
| - | 2 | - | -3.854 to -4.011 |
| - | 3 | - | -4.012 to -4.177 |
| 1 | 4 | - | -4.178 to -4.347 |
| 2 | 5 | - | -4.348 to -4.524 |
| 3 | 6 | - | -4.525 to -4.708 |
| 4 | 7 | 1 | -4.709 to -4.900 |
| 5 | 8 | 2 | -4.901 to -5.100 |
| 6 | 9 | 3 | -5.101 to -5.308 |
| 7 | - | 4 | -5.309 to -5.524 |
| 8 | - | 5 | -5.525 to -5.749 |
| 9 | - | 6 | -5.750 to -5.983 |
| - | - | 7 | -5.984 to -6.227 |
| - | - | 8 | -6.228 to -6.481 |
| - | - | 9 | -6.482 to -6.700 |
| * | * | * | Rejected article (for the manufacturing process control) |

Note: The chips of Ranking No. "*" are marked with the ink

## ON Current Deviation in a Chip

Test condition: VDD1 $=\mathrm{VDD} 2=5.0 \mathrm{~V}, \mathrm{VO}=1.6 \mathrm{~V}$, VREF $=1.8 \mathrm{~V}, \mathrm{Ta}=25^{\circ} \mathrm{C}$

1. Let the average ON current of the terminals DO4, 12, 20, 28, 36, 44, 52, and 60 be Cave, the that of the terminals DO1, 12, 20, and 28 be Lave, and that of the terminals DO36, 44, 52, and 60 be Rave: then the relationship among the Cave, Lave, and Rave should be as follows.
| Lave - Cave |/ Cave $\leq 2.5 \%, \mid$ Rave - Cave |/ Cave $\leq 2.5 \%$
2. Let the average ON current of DO1 to DO8, DO29 to DO36, and DO57 to DO64 be $\mathrm{I} 1, \mathrm{I} 2$, and I 3 , respectively: the relationship among the $\mathrm{I} 1, \mathrm{I} 2$, and I 3 should be as follows.
| In - Iave |/ Iave $\leq 2.5 \%$, Iave: Average ON current of the DO1 to DO64.
In: I2, and I3

## Timing Chart (SEL = High)



DOn(off) $\qquad$


## Pad Assignment



Chip size: $5.39 \mathrm{~mm} \times 1.43 \mathrm{~mm}$
Pad size: (PV open)
$110 \mu \mathrm{~m} \times 110 \mu \mathrm{~m}$ (Others)
$\Phi 110 \mu \mathrm{~m}$ (VDD2)
$100 \mu \mathrm{~m} \times 100 \mu \mathrm{~m}$ (DOn)
Chip thickness: $330 \mu \mathrm{~m} \pm 30 \mu \mathrm{~m}$

Pad Coordinates
Unit: $\mu \mathrm{m}$

| No. | Pin | X | Y | No. | Pin | X | Y |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 1 | SI | -2520 | -484 | 44 | DO22 | -840 | 398 |
| 2 | CLOCK1 | -2040 | -484 | 45 | DO23 | -760 | 539 |
| 3 | LOAD1 | -1800 | -484 | 46 | DO24 | -680 | 398 |
| 4 | VDD | -1560 | -484 | 47 | DO25 | -600 | 539 |
| 5 | VREF | -1080 | -484 | 48 | DO26 | -520 | 398 |
| 6 | SEL | -840 | -484 | 49 | DO27 | -440 | 539 |
| 7 | STROBE | -600 | -484 | 50 | DO28 | -360 | 398 |
| 8 | VSS | -120 | -484 | 51 | DO29 | -280 | 539 |
| 9 | NC | 120 | -484 | 52 | DO30 | -200 | 398 |
| 10 | ADJ(-) | 600 | -484 | 53 | DO31 | -120 | 539 |
| 11 | ADJ(+) | 840 | -484 | 54 | DO32 | -40 | 398 |
| 12 | VSS | 1080 | -484 | 55 | DO33 | 40 | 539 |
| 13 | VDD | 1560 | -484 | 56 | DO34 | 120 | 398 |
| 14 | LOAD2 | 1800 | -484 | 57 | DO35 | 200 | 539 |
| 15 | CLOCK2 | 2040 | -484 | 58 | DO36 | 280 | 398 |
| 16 | S0 | 2520 | -484 | 59 | DO37 | 360 | 539 |
| 17 | VDD2 | -2280 | 18 | 60 | DO38 | 440 | 398 |
| 18 | VDD2 | -1320 | 18 | 61 | DO39 | 520 | 539 |
| 19 | VDD2 | -360 | 18 | 62 | DO40 | 600 | 398 |
| 20 | VDD2 | 360 | 18 | 63 | DO41 | 680 | 539 |
| 21 | VDD2 | 1320 | 18 | 64 | DO42 | 760 | 398 |
| 22 | VDD2 | 2280 | 18 | 65 | DO43 | 840 | 539 |
| 23 | DO1 | -2520 | 539 | 66 | DO44 | 920 | 398 |
| 24 | D02 | -2440 | 398 | 67 | DO45 | 1000 | 539 |
| 25 | DO3 | -2360 | 539 | 68 | DO46 | 1080 | 398 |
| 26 | DO4 | -2280 | 398 | 69 | DO47 | 1160 | 539 |
| 27 | DO5 | -2200 | 539 | 70 | DO48 | 1240 | 398 |
| 28 | DO6 | -2120 | 398 | 71 | DO49 | 1320 | 539 |
| 29 | DO7 | -2040 | 539 | 72 | DO50 | 1400 | 398 |
| 30 | D08 | -1960 | 398 | 73 | DO51 | 1480 | 539 |
| 31 | D09 | -1880 | 539 | 74 | DO52 | 1560 | 398 |
| 32 | D010 | -1800 | 398 | 75 | D053 | 1640 | 539 |
| 33 | D011 | -1720 | 539 | 76 | D054 | 1720 | 398 |
| 34 | DO12 | -1640 | 398 | 77 | DO55 | 1800 | 539 |
| 35 | D013 | -1560 | 539 | 78 | DO56 | 1880 | 398 |
| 36 | DO14 | -1480 | 398 | 79 | DO57 | 1960 | 539 |
| 37 | DO15 | -1400 | 539 | 80 | DO58 | 2040 | 398 |
| 38 | DO16 | -1320 | 398 | 81 | DO59 | 2120 | 539 |
| 39 | DO17 | -1240 | 539 | 82 | DO60 | 2200 | 398 |
| 40 | D018 | -1160 | 398 | 83 | D061 | 2280 | 539 |
| 41 | D019 | -1080 | 539 | 84 | D062 | 2360 | 398 |
| 42 | DO20 | -1000 | 398 | 85 | D063 | 2440 | 539 |
| 43 | DO21 | -920 | 539 | 86 | DO64 | 2520 | 398 |

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